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## Product Change Notification - RMES-15LLWR349 (Printer Friendly)

**Date:**

23 Jun 2017

**Product Category:**

8-bit PIC Microcontrollers

**Notification subject:**

CCB 2873 and 2873.001-.004 Initial Notice: Qualification of CuPdAu bond wire for selected products of 250K and 290K wafer technology available in 8L,14L, 20L, 40L PDIP and 28L SPDIP packages at MMT.

**Notification text:****PCN Status:**

Initial notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of CuPdAu bond wire for selected products of 250K and 290K wafer technology available in 8L, 14L, 20L, 40L PDIP and 28L SPDIP packages at MMT assembly site.

**Pre Change:**

Assembled using gold (Au) bond wire

**Post Change:**

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire.

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	MMT	MMT
<b>Wire material</b>	Au	CuPdAu
<b>Die attach material</b>	CRM-1064L	CRM-1064L
<b>Molding compound material</b>	GE800	GE800
<b>Lead frame material</b>	CDA194	CDA194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by palladium coated copper with gold flash (CuPdAu) bond wire at MMT assembly site.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

August 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	June 2017					->	August 2017				
	22	23	24	25	26		31	32	33	34	35
Initial PCN Issue Date				X							
Qualification Report Availability											X
Final PCN Issue Date											X

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

**Revision History:****June 23, 2017:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**[PCN\\_RMES-15LLWR349\\_Qual\\_Plan1.pdf](#)[PCN\\_RMES-15LLWR349\\_Affected\\_CPN.pdf](#)[PCN\\_RMES-15LLWR349\\_Affected\\_CPN.xlsx](#)

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